

# SOT1622-3

BGA783, plastic, ball grid array; 783 balls; 1 mm pitch; 29 mm x 29 mm x 2.76 mm body

31 August 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	BGA783
<b>Package style descriptive code</b>	BGA (ball grid array)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MS-034B AAM-1
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	22-12-2015
<b>Manufacturer package code</b>	98ARE10717D

**Table 1. Package summary**

Parameter	Min	Nom	Max	Unit
package length	-	29	-	mm
package width	-	29	-	mm
package height	-	2.76	-	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	783	-	



2 Package outline

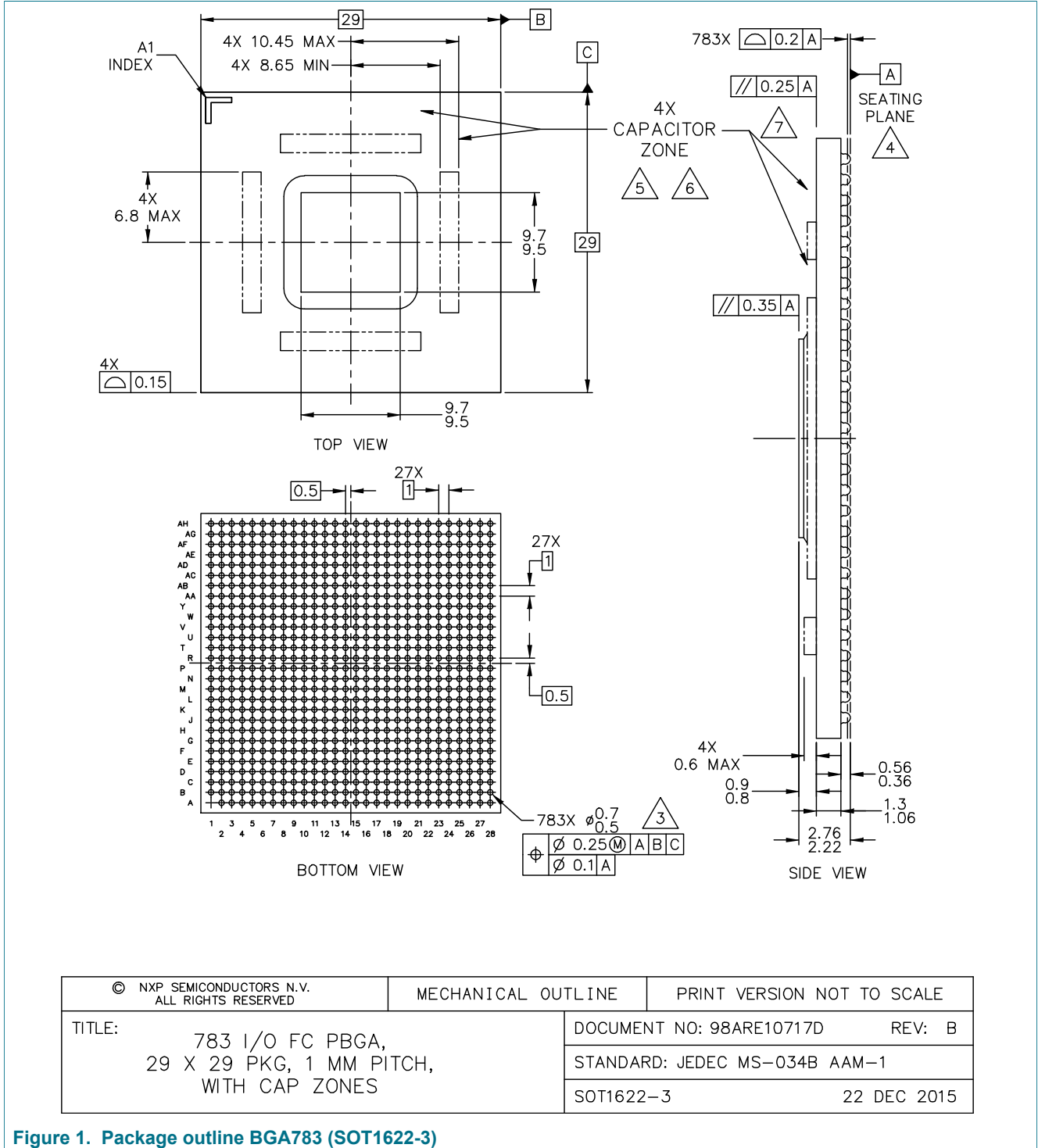


Figure 1. Package outline BGA783 (SOT1622-3)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.
6. CAUTION MUST BE TAKEN NOT TO SHORT CAPACITORS OR EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.
7. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
8. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.

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TITLE: 783 I/O FC PBGA, 29 X 29 PKG, 1 MM PITCH, WITH CAP ZONES	DOCUMENT NO: 98ARE10717D	REV: B
	STANDARD: JEDEC MS-034B AAM-1	
	SOT1622-3	22 DEC 2015

Figure 2. Package outline note BGA783 (SOT1622-3)

### 3 Legal information

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